WHAT IS CLAIMED IS:

1. A method for processing a plurality of microelectromechanical-systems (MEMS) dice, the method comprising:

securing the plurality of MEMS dice in a holder; and

performing a process step on the plurality of MEMS dice while secured in the holder.

2. The method recited in claim 1 wherein the process step is performed simultaneously on the MEMS dice while secured in the holder.

3. The method recited in claim 1 wherein the plurality of MEMS dice include unreleased MEMS dice.

4. The method recited in claim 1 wherein performing the process step comprises immersing the holder with the plurality of secured MEMS dice in a liquid.

5. The method recited in claim 4 wherein the liquid comprises a solution of hydrofluoric acid.

6. The method recited in claim 4 wherein the liquid comprises deionized water.

7. The method recited in claim 4 wherein performing the process step further comprises immersing the holder with the plurality of secured MEMS dice in a second liquid.

8. The method recited in claim 4 wherein performing the process step further comprises performing critical point drying on the plurality of MEMS dice.

9. The method recited in claim 1 wherein performing the process step comprises testing the plurality of MEMS dice.

10. The method recited in claim 1 wherein performing the process step comprises performing a step in packaging the plurality of MEMS dice.

11. The method recited in claim 1 further comprising removing the plurality of MEMS dice from the holder after performing the process step.

12. The method recited in claim 1 wherein the holder is made of a fluoropolymer resin.

13. The method recited in claim 12 wherein the holder is made of teflon®.

14. The method recited in claim 1 further comprising preparing the plurality of MEMS dice by dicing a processed wafer.

15. An article comprising:

a structural body having a plurality of stations, each such station being adapted to secure a microelectromechanical-systems (MEMS) die.

16. The article recited in claim 15 wherein each such station comprises:

a recess within the structural body shaped to secure an edge of the MEMS die; and

a flexible retaining arm adapted to retain the MEMS die within the recess.

17. The article recited in claim 16 wherein the flexible retaining arm includes a notch shaped for engagement with a tool for flexing the flexible retaining arm.

18. The article recited in claim 15 wherein each such station includes an access to an underside of the MEMS die.

19. The article recited in claim 18 wherein the access comprises a hole in the structural body.

20. The article recited in claim 18 wherein the access comprises a slot in the structural body.

21. The article recited in claim 15 wherein the structural body is circularly symmetric and the plurality of stations are configured symmetrically about a central axis of the structural body.

22. The article recited in claim 15 wherein the article is formed as a single continuous structure.

23. The article recited in claim 22 wherein the article is formed of a fluoropolymer resin.

24. The article recited in claim 23 wherein the article is formed of teflon®.

25. An article comprising:

a structural body having a plurality of means for securing a microelectromechanical-systems (MEMS) die.

26. The article recited in claim 25 wherein each such means for securing includes flexible means for retaining the MEMS die within a recess in the structural body.

27. The article recited in claim 25 wherein the structural body is circularly symmetric and the plurality of means for securing are configured symmetrically about a central axis of the structural body.